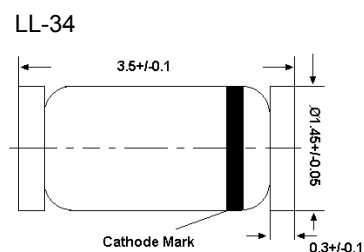


Fast switching diode in MiniMELF case especially suited for automatic surface mounting



Glass case MiniMELF
Dimensions in mm

Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

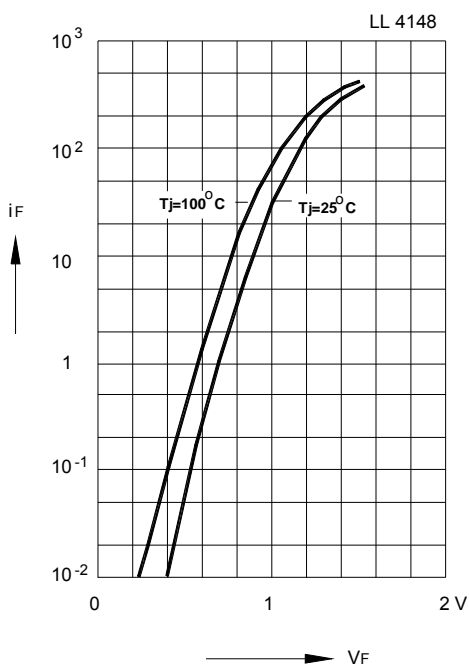
Parameter	Symbol	Value	Unit
Peak Reverse Voltage	V_{RM}	100	V
Reverse Voltage	V_R	75	V
Average Rectified Forward Current	$I_{F(AV)}$	200	mA
Non-repetitive Peak Forward Surge Current	I_{FSM}	0.5	A
at $t = 1\text{ s}$		1	
at $t = 1\text{ ms}$		4	
Power Dissipation	P_{tot}	500 ¹⁾	mW
Junction Temperature	T_j	175	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	- 65 to + 175	$^\circ\text{C}$

¹⁾ Valid provided that electrodes are kept at ambient temperature.

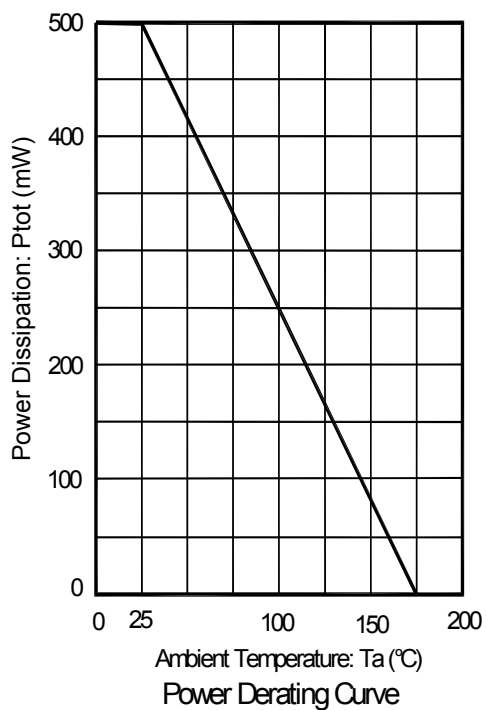
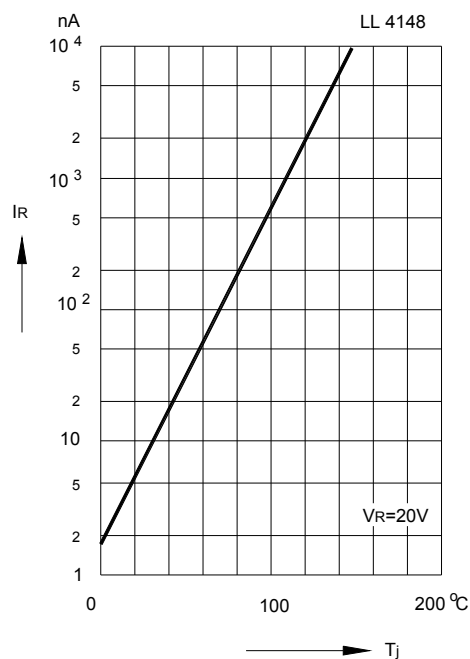
Characteristics at $T_a = 25^\circ\text{C}$

Parameter	Symbol	Min.	Max.	Unit
Reverse Breakdown Voltage tested with 100 μA Pulses	$V_{(BR)R}$	100	-	V
Forward Voltage at $I_F = 10 \text{ mA}$	V_F	-	1	V
Leakage Current at $V_R = 20 \text{ V}$ at $V_R = 75 \text{ V}$ at $V_R = 20 \text{ V}$, $T_j = 150^\circ\text{C}$	I_R I_R I_R	- - -	25 5 50	nA μA μA
Capacitance at $V_R = 0$, $f = 1 \text{ MHz}$	C_{tot}	-	4	pF
Voltage Rise when Switching ON tested with 50 mA Forward Pulses $t_p = 0.1 \text{ s}$, Rise Time < 30 ns, $f_p = 5$ to 100 KHz	V_{fr}	-	2.5	V
Reverse Recovery Time at $I_F = 10 \text{ mA}$ to $I_R = 1 \text{ mA}$, $I_{\text{rr}} = 0.1 \times I_R$, $V_R = 6 \text{ V}$, $R_L = 100 \Omega$	t_{rr}	-	4	ns

Forward characteristics



Leakage current versus junction temperature



Relative capacitance versus reverse voltage

